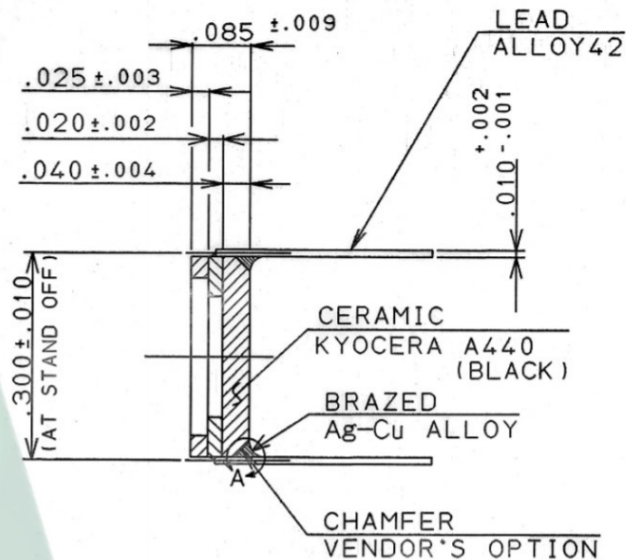
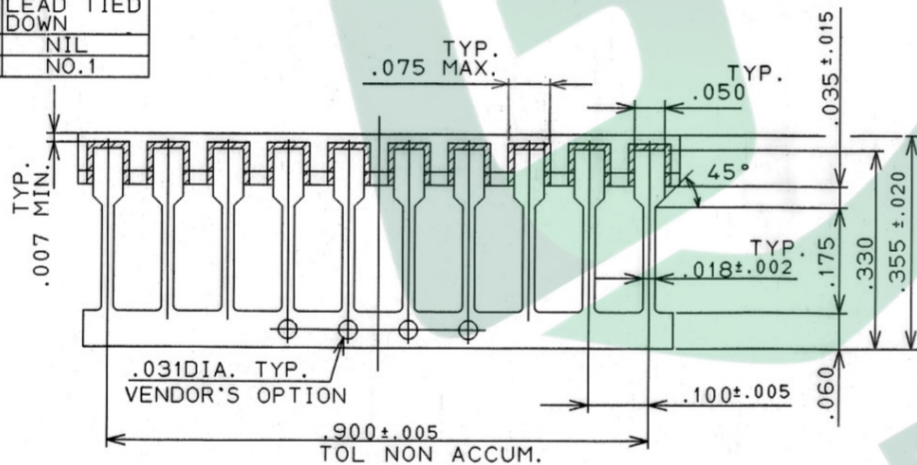


PART NO.	INDEX MARK	LEAD TIED DOWN
-01	●	NIL
-02	⊥	NO.1



DETAIL-A

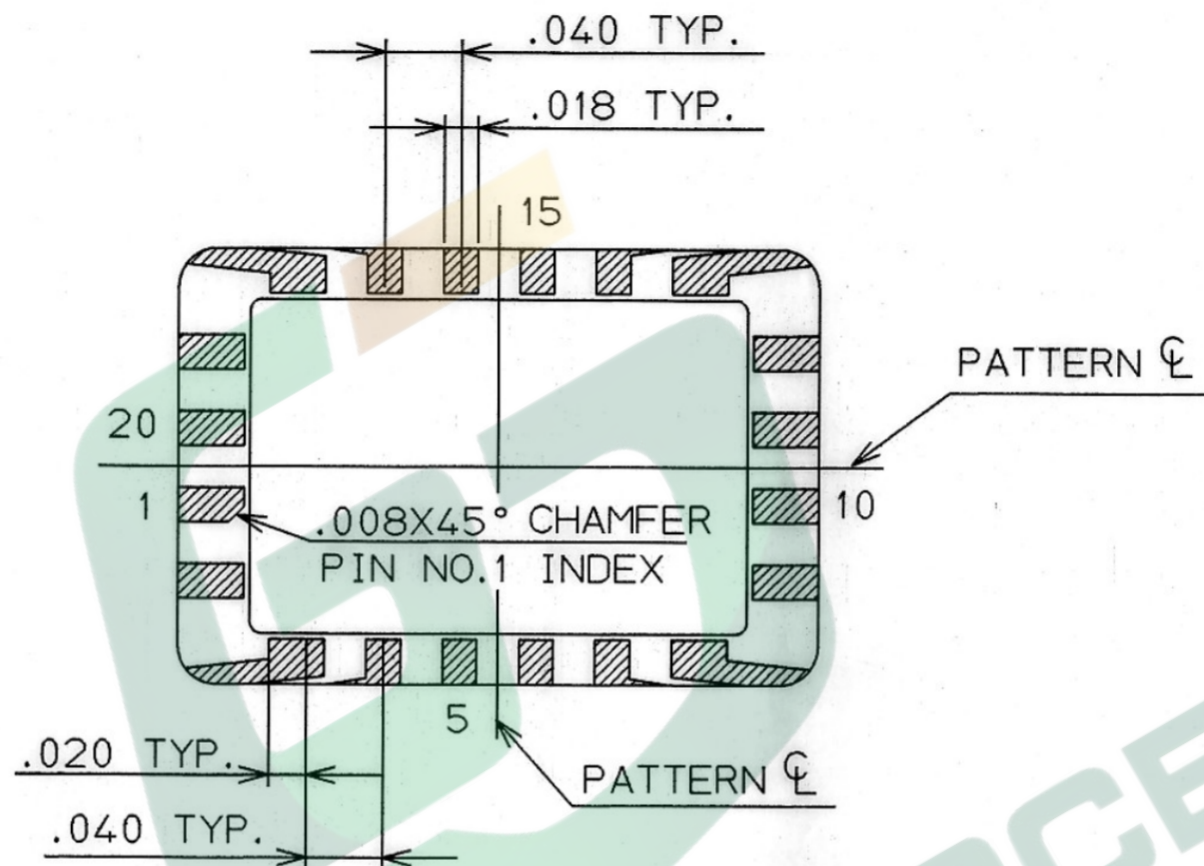
NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. LEAD RESISTANCE : 0.3 Ω MAX.



上海季丰电子科技有限公司  
GIGA FORCE ELECTRONICS CO., Limited

制图	胡熠文	Title	DIP20	
核准	何桂港	POD No	POD-SHJF-46	
日期	2023. 1. 31	DIMENSIONS IN:	in	Rev:A



BONDING PATTERN



上海季丰电子科技有限公司  
GIGA FORCE ELECTRONICS CO., Limited

制图	胡熠文	Title	DIP20		
核准	何桂港	POD No	POD-SHJF-46		
日期	2023. 1. 31	DIMENSIONS IN:	in	Rev:A	